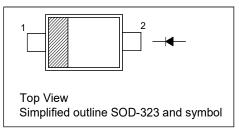
Silicon Epitaxial Planar Switching Diode

Features

- AEC-Q101 Qualified
- Ultra high speed switching application
- · Low forward voltage
- Fast reverse recovery time
- Small total capacitance
- Halogen and Antimony Free(HAF), RoHS compliant

PINNING

| PIN | DESCRIPTION | | |
|-----|-------------|--|--|
| 1 | Cathode | | |
| 2 | Anode | | |



Absolute Maximum Ratings (T_a = 25 °C)

| Parameter | Symbol | Value | Unit |
|-----------------------------------|--------------------|--------------------|------|
| Peak Reverse Voltage | V_{RM} | V _{RM} 85 | |
| Reverse Voltage | V _R 80 | | V |
| Average Rectified Forward Current | I _{F(AV)} | 100 | mA |
| Peak Forward Current | I _{FM} | 300 | mA |
| Surge Forward Current (10 ms) | I _{FSM} | 2 | А |
| Power Dissipation | P _{tot} | 150 | mW |
| Junction Temperature | T _j 150 | | °C |
| Storage Temperature Range | T _{stg} | - 55 to + 150 | °C |

Thermal Characteristics

| Parameter | Symbol | Max. | Unit |
|--|----------------|------|------|
| Thermal Resistance from Junction to Ambient 1) | $R_{	heta JA}$ | 833 | °C/W |

¹⁾Device mounted on FR-4 substrate PC board, with minimum recommended pad layout.



1SS511WS-AH

Characteristics at $T_a = 25 \circ C$

| Parameter | Symbol | Min. | Max. | Unit |
|---|--------------------|------|------|------|
| Reverse Breakdown Voltage at $I_R = 10 \mu A$ | V _{(BR)R} | 80 | - | V |
| Forward Voltage at I _F = 100 mA | V _F | - | 1.2 | V |
| Reverse Current at $V_R = 80 \text{ V}$ | I _R | - | 0.5 | μΑ |
| Total Capacitance at $V_R = 0 \text{ V}$, $f = 1 \text{ MHz}$ | C _{tot} | - | 4 | pF |
| Reverse Recovery Time at I _F = 10 mA, I _{RR} = 0.1 * I _R , V_R = 6 V, R_L = 100 Ω | t _{rr} | - | 4 | ns |



Electrical Characteristics Curves

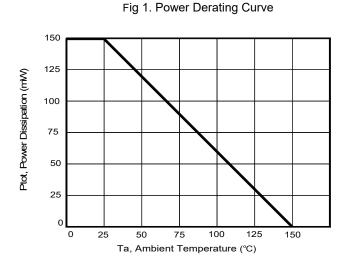


Fig 2. Total Capacitance vs. Reverse Voltage

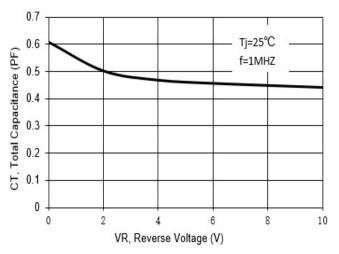


Fig 3. Reverse Current vs. Reverse Voltage

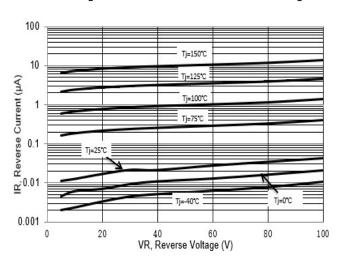
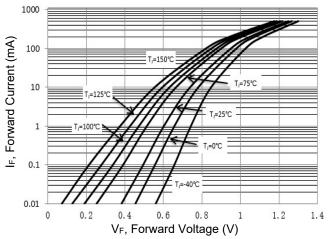


Fig 4. Forward Characteristics

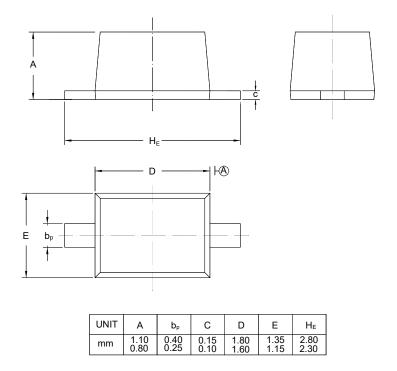




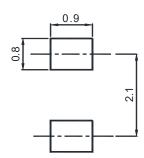
PACKAGE OUTLINE

Plastic surface mounted package; 2 leads

SOD-323



Recommended Soldering Footprint



Packing information

| Package | Tape Width | Pit | Pitch | | Size | Por Pool Pooking Quantity | |
|---------|------------|---------|---------------|-----|--------|---------------------------|--|
| Fackage | (mm) | mm | (inch) | mm | (inch) | Per Reel Packing Quantity | |
| SOD-323 | 8 | 4 ± 0.1 | 0.157 ± 0.004 | 178 | 7 | 3,000 | |

Marking information

" W2 " = Part No.

" III " = Cathode line

" • " = HAF (Halogen and Antimony Free)

Font type: Arial



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